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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	71
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 20x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	80-LQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f212c8snfp-v2

Table 1.3 Specifications for R8C/2D Group (1)

Item	Function	Specification
CPU	Central processing unit	R8C/Tiny series core • Number of fundamental instructions: 89 • Minimum instruction execution time: 50 ns ($f(XIN) = 20$ MHz, $VCC = 3.0$ to 5.5 V) 100 ns ($f(XIN) = 10$ MHz, $VCC = 2.7$ to 5.5 V) 200 ns ($f(XIN) = 5$ MHz, $VCC = 2.2$ to 5.5 V) • Multiplier: 16 bits $\times$ 16 bits $\rightarrow$ 32 bits • Multiply-accumulate instruction: 16 bits $\times$ 16 bits + 32 bits $\rightarrow$ 32 bits • Operation mode: Single-chip mode (address space: 1 Mbyte)
Memory	ROM, RAM	Refer to Table 1.6 Product List for R8C/2D Group .
Power Supply Voltage Detection	Voltage detection circuit	• Power-on reset • Voltage detection 3
I/O Ports	Programmable I/O ports	• Input-only: 2 pins • CMOS I/O ports: 71, selectable pull-up resistor • High current drive ports: 8
Clock	Clock generation circuits	3 circuits: XIN clock oscillation circuit (with on-chip feedback resistor), On-chip oscillator (high-speed, low-speed) (high-speed on-chip oscillator has a frequency adjustment function), XCIN clock oscillation circuit (32 kHz) • Oscillation stop detection: XIN clock oscillation stop detection function • Frequency divider circuit: Dividing selectable 1, 2, 4, 8, and 16 • Low power consumption modes: - Standard operating mode (high-speed clock, low-speed clock, high-speed on-chip oscillator, low-speed on-chip oscillator), wait mode, stop mode
		Real-time clock (timer RE)
Interrupts		• External: 5 sources, Internal: 23 sources, Software: 4 sources • Priority levels: 7 levels
Watchdog Timer		15 bits $\times$ 1 (with prescaler), reset start selectable
Timer	Timer RA	8 bits $\times$ 1 (with 8-bit prescaler) Timer mode (period timer), pulse output mode (output level inverted every period), event counter mode, pulse width measurement mode, pulse period measurement mode
	Timer RB	8 bits $\times$ 1 (with 8-bit prescaler) Timer mode (period timer), programmable waveform generation mode (PWM output), programmable one-shot generation mode, programmable wait one-shot generation mode
	Timer RC	16 bits $\times$ 1 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 3 pins), PWM2 mode (PWM output pin)
	Timer RD	16 bits $\times$ 2 (with 4 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 6 pins), reset synchronous PWM mode (output three-phase waveforms (6 pins), sawtooth wave modulation), complementary PWM mode (output three-phase waveforms (6 pins), triangular wave modulation), PWM3 mode (PWM output 2 pins with fixed period)
	Timer RE	8 bits $\times$ 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits $\times$ 1 (with capture/compare register pin and compare register pin) Input capture mode, output compare mode

1.4 Pin Assignment

Figure 1.4 shows Pin Assignment (Top View). Tables 1.7 and 1.8 outlines the Pin Name Information by Pin Number.

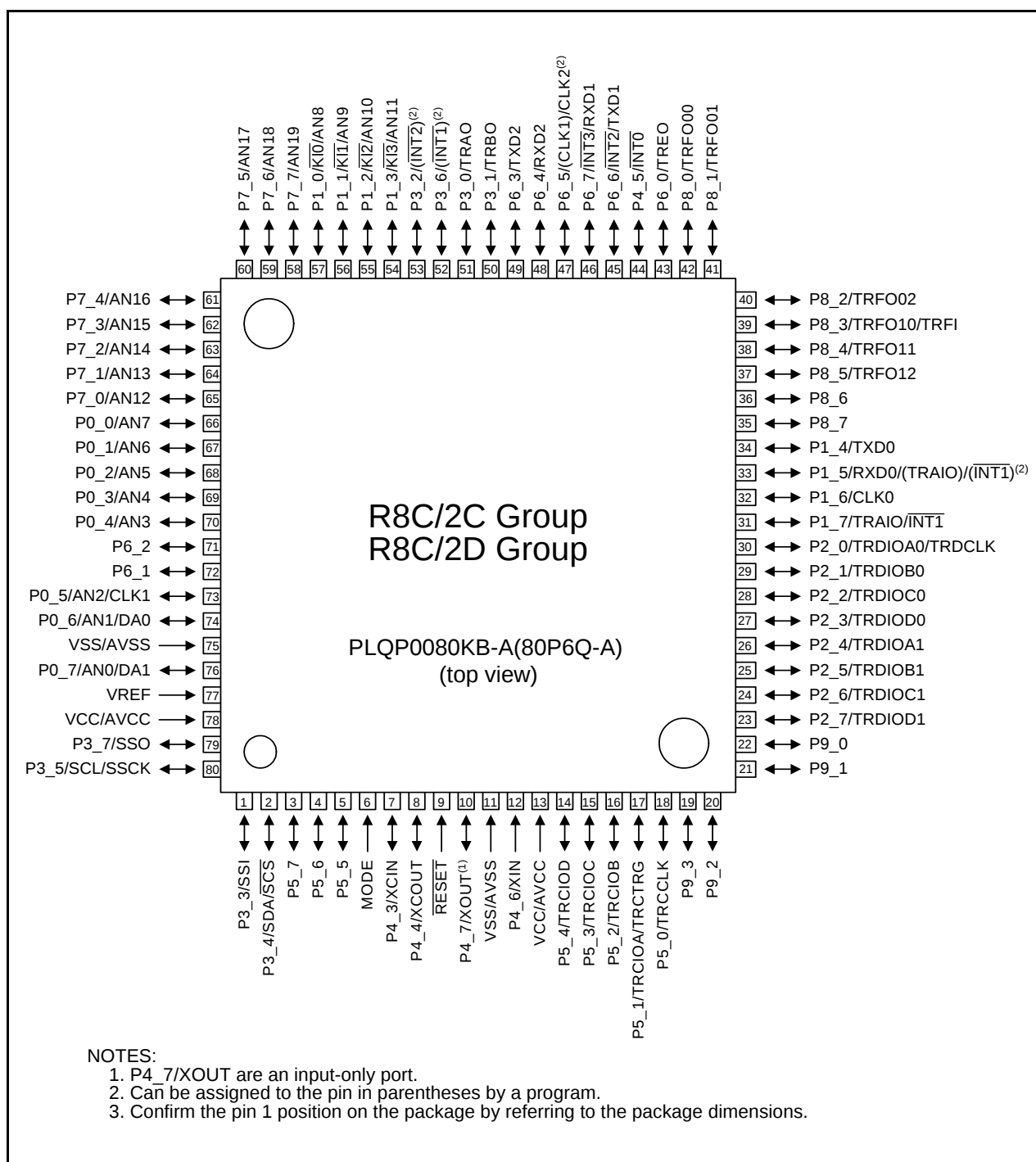


Figure 1.4 Pin Assignment (Top View)

3. Memory

3.1 R8C/2C Group

Figure 3.1 is a Memory Map of R8C/2C Group. The R8C/2C group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM area is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

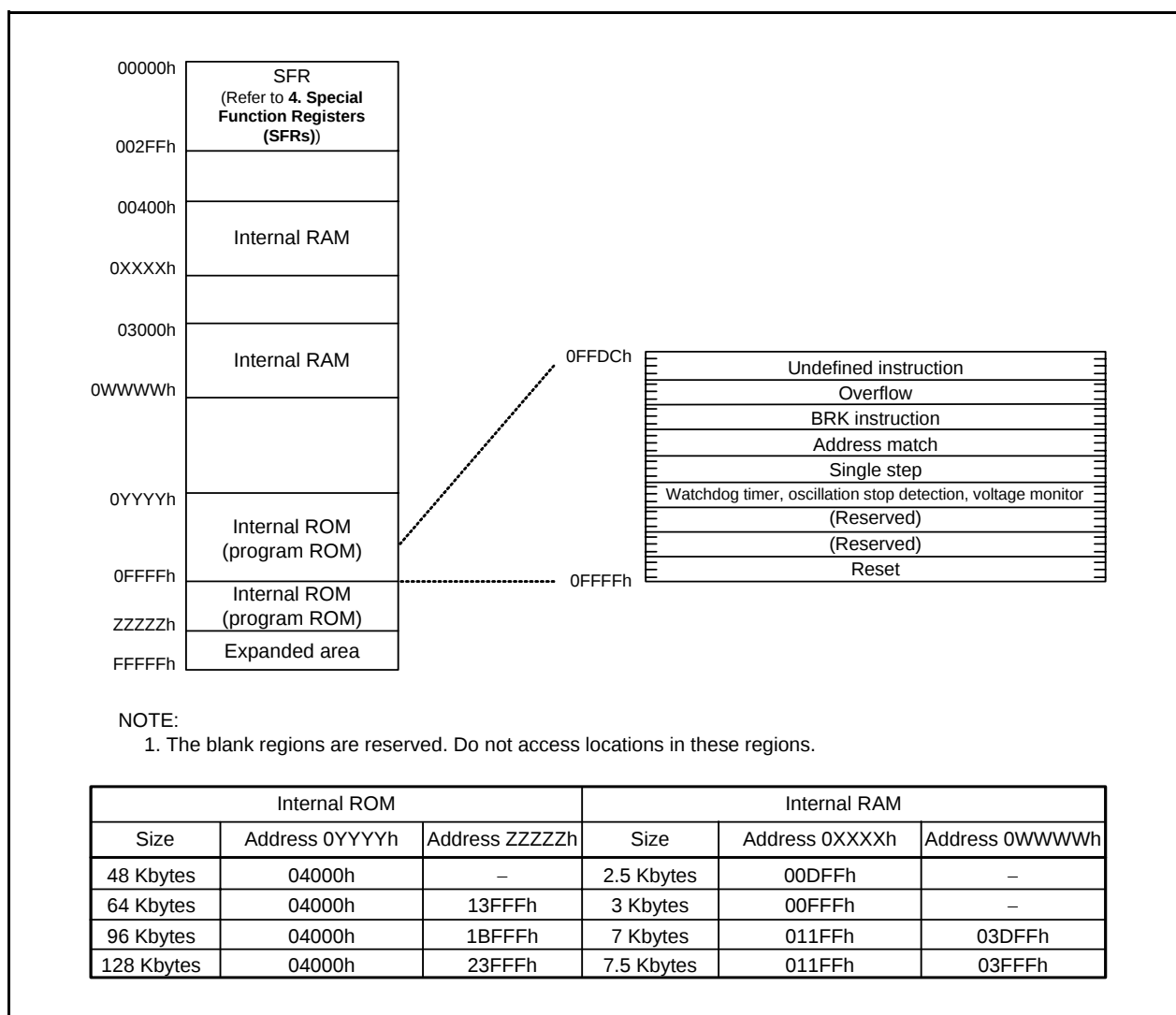


Figure 3.1 Memory Map of R8C/2C Group

3.2 R8C/2D Group

Figure 3.2 is a Memory Map of R8C/2D Group. The R8C/2D group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM area is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

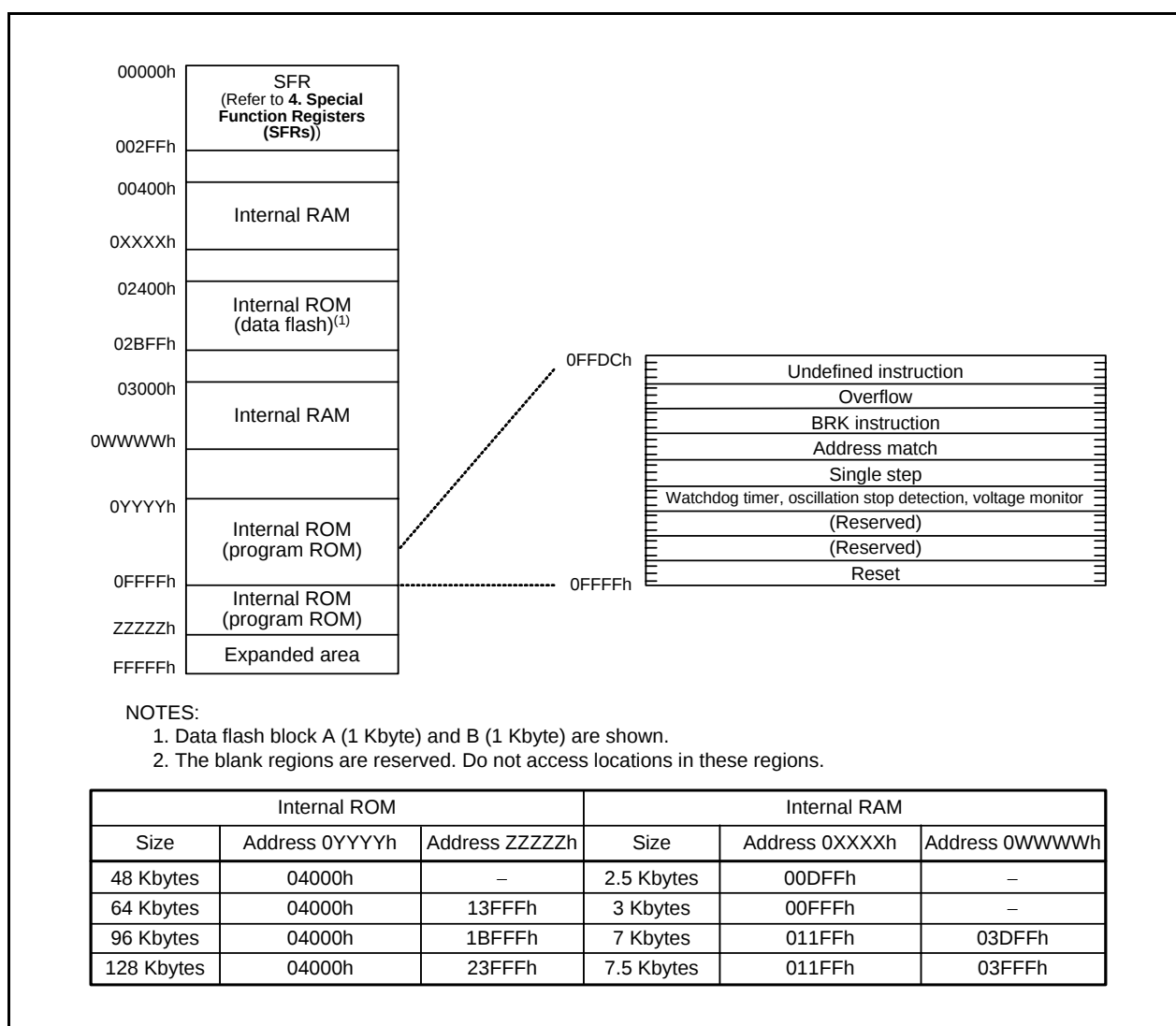


Figure 3.2 Memory Map of R8C/2D Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Operation Enable Register	MSTCR	00h
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽⁶⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h			
002Ah			
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When Shipping
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 00100000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽²⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Ah			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect this register.
3. The LVD0ON bit in the OFS register is set to 1 and hardware reset.
4. Power-on reset, voltage monitor 0 reset, or the LVD0ON bit in the OFS register is set to 0 and hardware reset.
5. Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect b2 and b3.
6. The CSPROINI bit in the OFS register is set to 0.

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh			
004Fh	SSU/IIC Interrupt Control Register ⁽²⁾	SSUIC / IICIC	XXXXX000b
0050h	Compare 1 Interrupt Control Register	CMP1IC	XXXXX000b
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh	Timer RF Interrupt Control Register	TRFIC	XXXXX000b
005Ch	Compare 0 Interrupt Control Register	CMP0IC	XXXXX000b
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
005Fh	Capture Interrupt Control Register	CAPIC	XXXXX000b
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.7 SFR Information (7)⁽¹⁾

Address	Register	Symbol	After reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.10 SFR Information (10)(1)

Address	Register	Symbol	After reset
0240h			
0241h			
0242h			
0243h			
0244h			
0245h			
0246h			
0247h			
0248h			
0249h			
024Ah			
024Bh			
024Ch			
024Dh			
024Eh			
024Fh			
0250h			
0251h			
0252h			
0253h			
0254h			
0255h			
0256h			
0257h			
0258h			
0259h			
025Ah			
025Bh			
025Ch			
025Dh			
025Eh			
025Fh			
0260h			
0261h			
0262h			
0263h			
0264h			
0265h			
0266h			
0267h			
0268h			
0269h			
026Ah			
026Bh			
026Ch			
026Dh			
026Eh			
026Fh			
0270h			
0271h			
0272h			
0273h			
0274h			
0275h			
0276h			
0277h			
0278h			
0279h			
027Ah			
027Bh			
027Ch			
027Dh			
027Eh			
027Fh			

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

5. Electrical Characteristics

The electrical characteristics of N version ($T_{opr} = -20^{\circ}\text{C}$ to 85°C) and D version ($T_{opr} = -40^{\circ}\text{C}$ to 85°C) are listed below.

Please contact Renesas Technology sales offices for the electrical characteristics in the Y version ($T_{opr} = -20^{\circ}\text{C}$ to 105°C).

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{cc}/AV_{cc}	Supply voltage		-0.3 to 6.5	V
V_i	Input voltage		-0.3 to $V_{cc} + 0.3$	V
V_o	Output voltage		-0.3 to $V_{cc} + 0.3$	V
P_d	Power dissipation	$T_{opr} = 25^{\circ}\text{C}$	700	mW
T_{opr}	Operating ambient temperature		-20 to 85 (N version) / -40 to 85 (D version)	$^{\circ}\text{C}$
T_{stg}	Storage temperature		-65 to 150	$^{\circ}\text{C}$

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V _{CC} /AV _{CC}	Supply voltage			2.2	–	5.5	V
V _{SS} /AV _{SS}	Supply voltage			–	0	–	V
V _{IH}	Input “H” voltage			0.8 V _{CC}	–	V _{CC}	V
V _{IL}	Input “L” voltage			0	–	0.2 V _{CC}	V
I _{OH} (sum)	Peak sum output “H” current	Sum of all pins I _{OH} (peak)		–	–	–240	mA
I _{OH} (sum)	Average sum output “H” current	Sum of all pins I _{OH} (avg)		–	–	–120	mA
I _{OH} (peak)	Peak output “H” current	Except P2_0 to P2_7		–	–	–10	mA
		P2_0 to P2_7		–	–	–40	mA
I _{OH} (avg)	Average output “H” current	Except P2_0 to P2_7		–	–	–5	mA
		P2_0 to P2_7		–	–	–20	mA
I _{OL} (sum)	Peak sum output “L” current	Sum of all pins I _{OL} (peak)		–	–	240	mA
I _{OL} (sum)	Average sum output “L” current	Sum of all pins I _{OL} (avg)		–	–	120	mA
I _{OL} (peak)	Peak output “L” current	Except P2_0 to P2_7		–	–	10	mA
		P2_0 to P2_7		–	–	40	mA
I _{OL} (avg)	Average output “L” current	Except P2_0 to P2_7		–	–	5	mA
		P2_0 to P2_7		–	–	20	mA
f _(XIN)	XIN clock input oscillation frequency		3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
f _(XCIN)	XCIN clock input oscillation frequency		2.2 V ≤ V _{CC} ≤ 5.5 V	0	–	70	kHz
–	System clock	OCD2 = 0 XIN clock selected	3.0 V ≤ V _{CC} ≤ 5.5 V	0	–	20	MHz
			2.7 V ≤ V _{CC} < 3.0 V	0	–	10	MHz
			2.2 V ≤ V _{CC} < 2.7 V	0	–	5	MHz
		OCD2 = 1 On-chip oscillator clock selected	FRA01 = 0 Low-speed on-chip oscillator clock selected	–	125	–	kHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 3.0 V ≤ V _{CC} ≤ 5.5 V	–	–	20	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.7 V ≤ V _{CC} ≤ 5.5 V	–	–	10	MHz
			FRA01 = 1 High-speed on-chip oscillator clock selected 2.2 V ≤ V _{CC} ≤ 5.5 V	–	–	5	MHz

NOTES:

- V_{CC} = 2.2 to 5.5 V at T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
- The average output current indicates the average value of current measured during 100 ms.

Table 5.5 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/2C Group	100 ⁽³⁾	–	–	times
		R8C/2D Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97+CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3+CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.2	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60°C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erase count of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

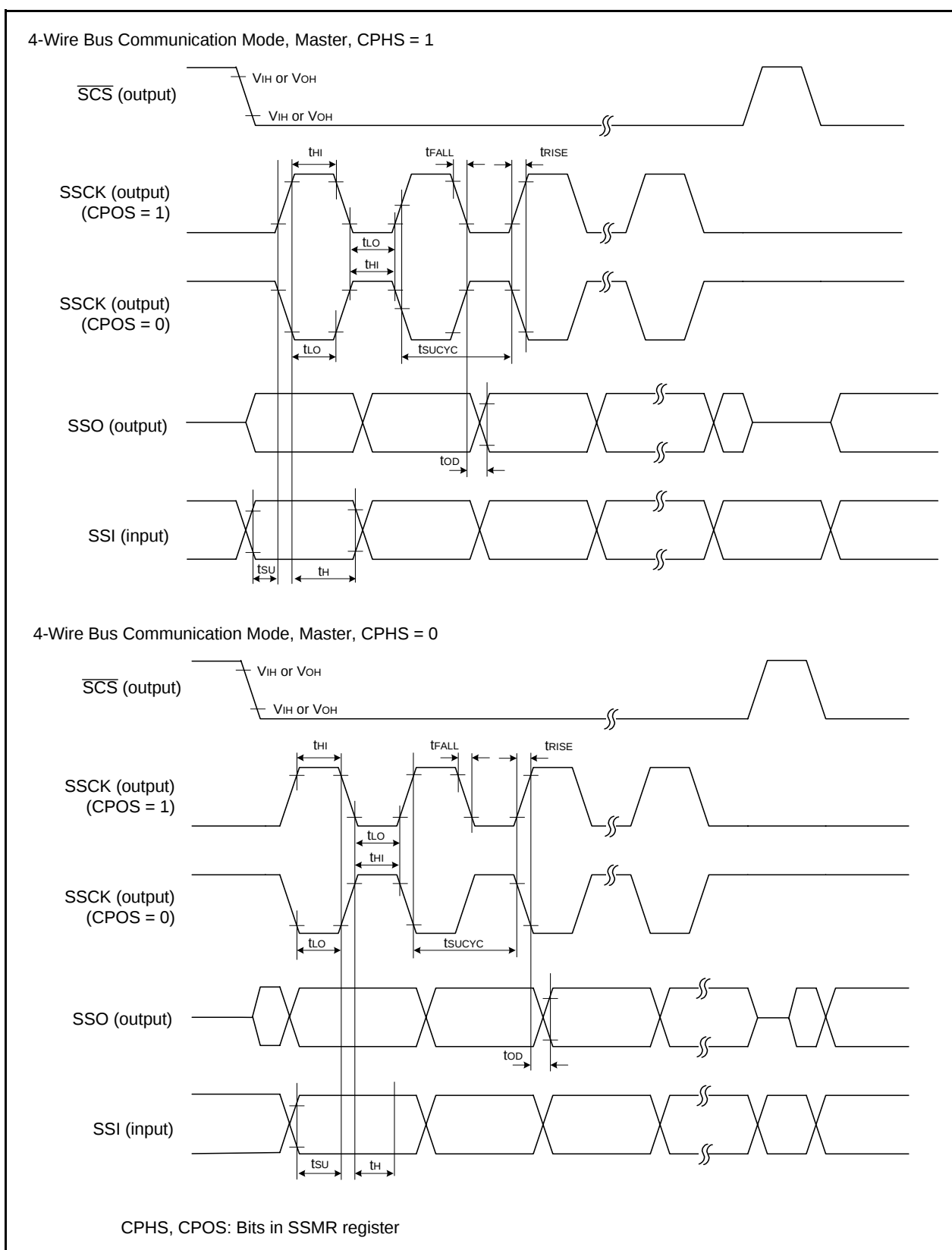


Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

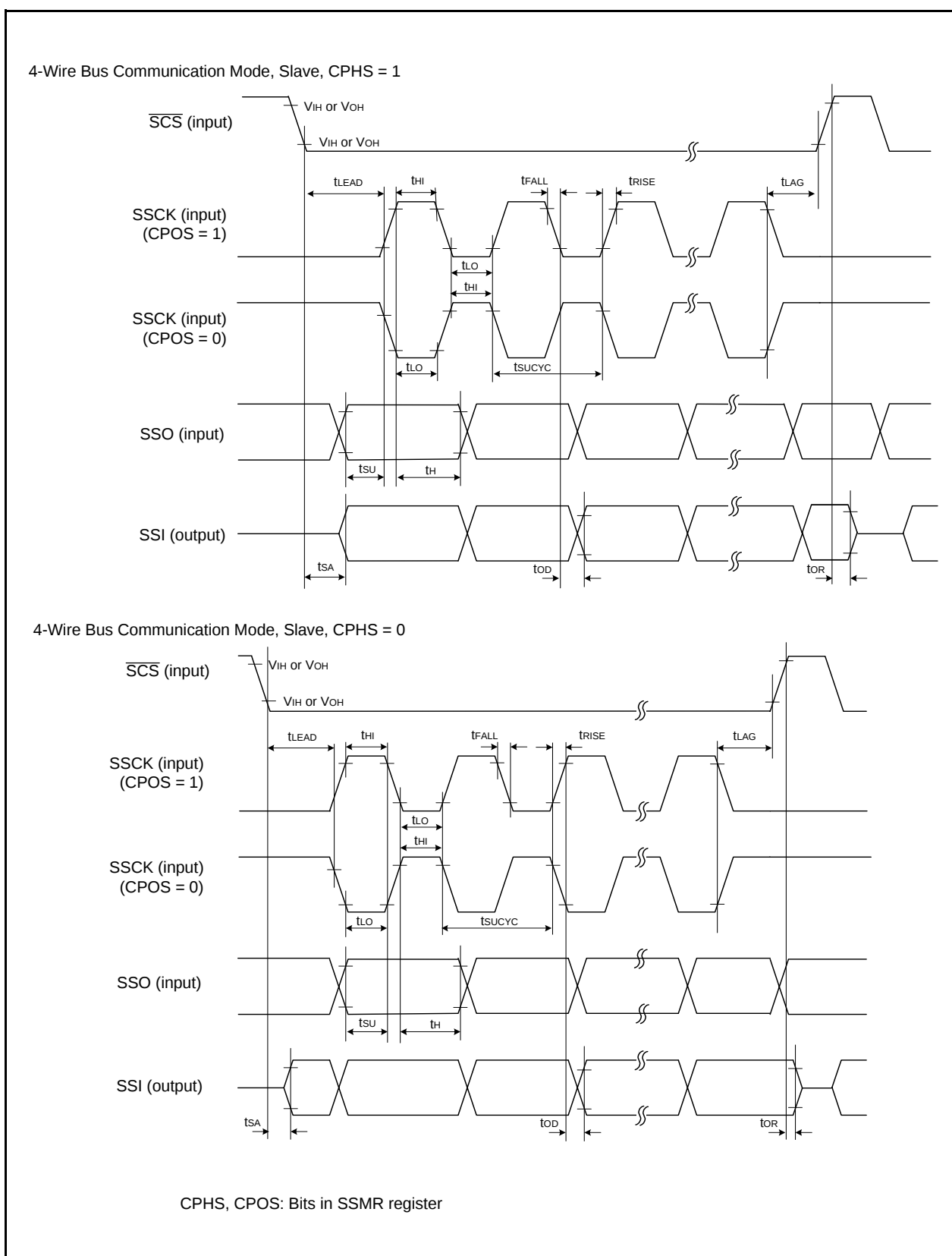


Figure 5.5 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

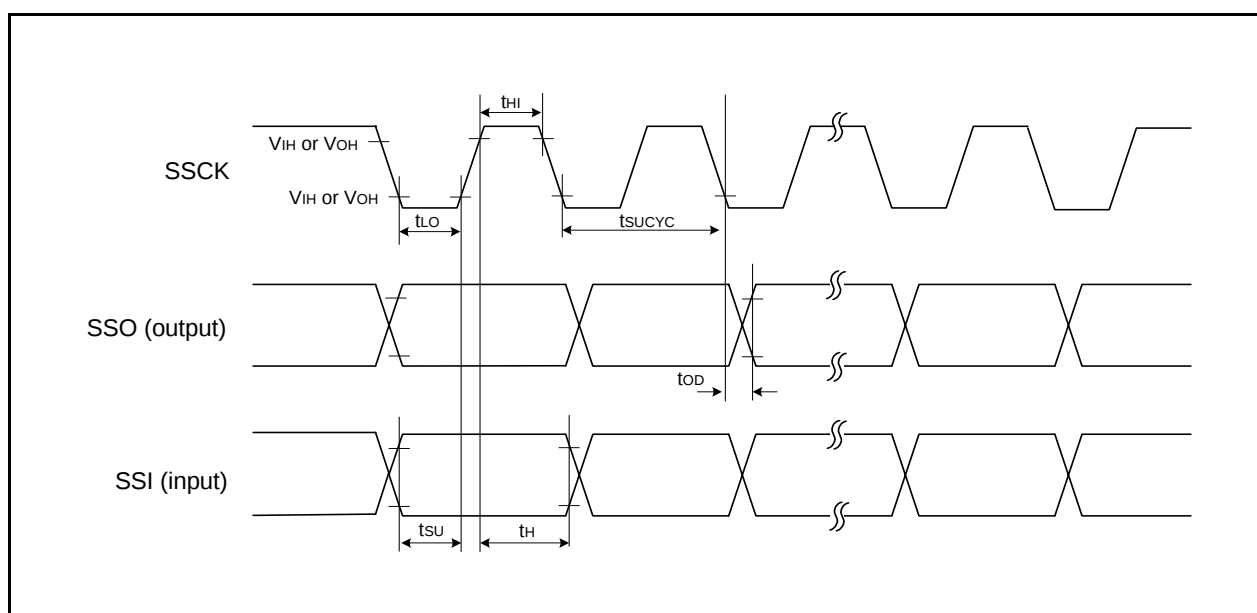


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.15 Timing Requirements of I²C bus Interface (1)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _{SCL}	SCL input cycle time		12tcyc + 600 ⁽²⁾	–	–	ns
t _{SCLH}	SCL input “H” width		3tcyc + 300 ⁽²⁾	–	–	ns
t _{SCLL}	SCL input “L” width		5tcyc + 500 ⁽²⁾	–	–	ns
t _{sf}	SCL, SDA input fall time		–	–	300	ns
t _{SP}	SCL, SDA input spike pulse rejection time		–	–	1tcyc ⁽²⁾	ns
t _{BUF}	SDA input bus-free time		5tcyc ⁽²⁾	–	–	ns
t _{STAH}	Start condition input hold time		3tcyc ⁽²⁾	–	–	ns
t _{STAS}	Retransmit start condition input setup time		3tcyc ⁽²⁾	–	–	ns
t _{STOP}	Stop condition input setup time		3tcyc ⁽²⁾	–	–	ns
t _{SDAS}	Data input setup time		1tcyc + 20 ⁽²⁾	–	–	ns
t _{SDAH}	Data input hold time		0	–	–	ns

NOTES:

1. V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V and T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.
2. 1tcyc = 1/f₁(s)

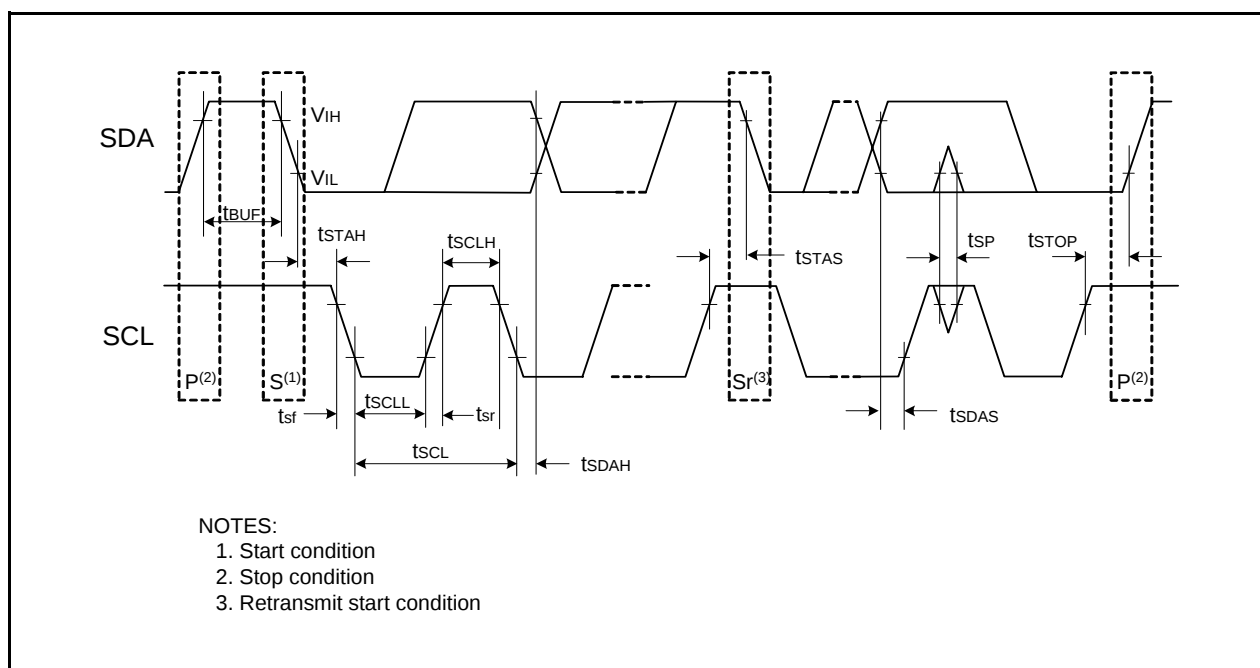
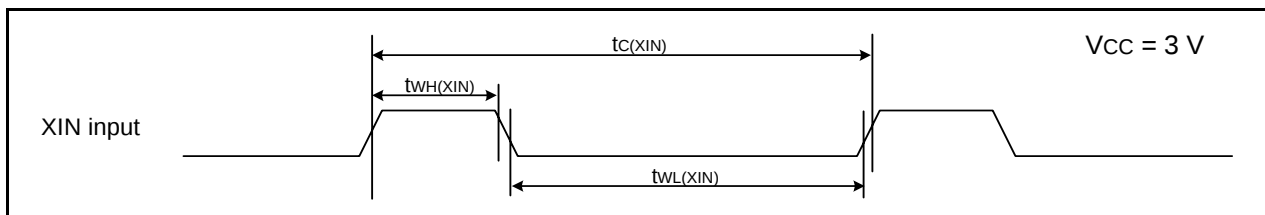
**Figure 5.7 I/O Timing of I²C bus Interface**

Table 5.24 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = –20 to 85°C (N version) / –40 to 85°C (D version), unless otherwise specified.)

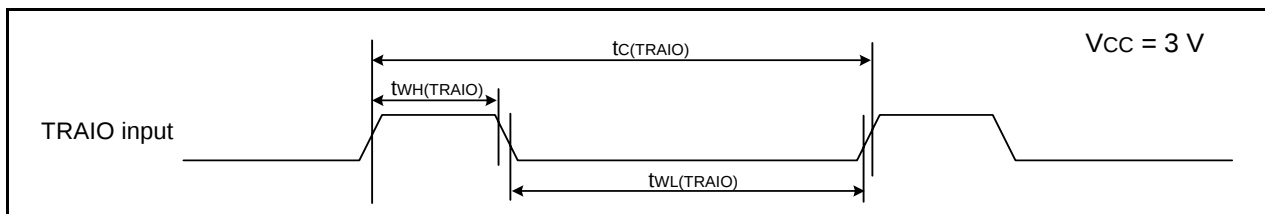
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	–	5.5	–	mA
				2	–	
		High-speed on-chip oscillator mode	–	5.5	11	mA
				2.2	–	
		Low-speed on-chip oscillator mode	–	145	400	μA
				145	400	
		Low-speed clock mode	–	30	–	μA
				–	–	
		Wait mode	–	28	85	μA
				17	50	
				3.3	–	
				2.1	–	
		Stop mode	–	0.65	3.0	μA
				1.65	–	

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^\circ\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.25 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.13 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.26 TRAIO Input, $\overline{\text{INT1}}$ Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

**Figure 5.14 TRAIO Input and $\overline{\text{INT1}}$ Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.27 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRFI)}$	TRFI input cycle time	1200 ⁽¹⁾	–	ns
$t_{WH(TRFI)}$	TRFI input “H” width	600 ⁽²⁾	–	ns
$t_{WL(TRFI)}$	TRFI input “L” width	600 ⁽²⁾	–	ns

NOTES:

1. When using timer RF input capture mode, adjust the cycle time to $(1/\text{timer RF count source frequency} \times 3)$ or above.
2. When using timer RF input capture mode, adjust the pulse width to $(1/\text{timer RF count source frequency} \times 1.5)$ or above.

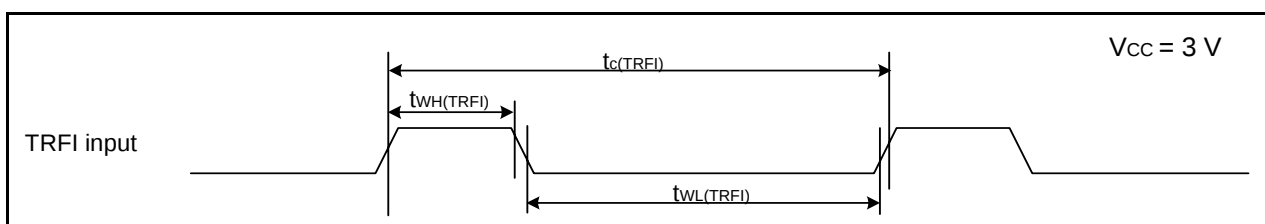
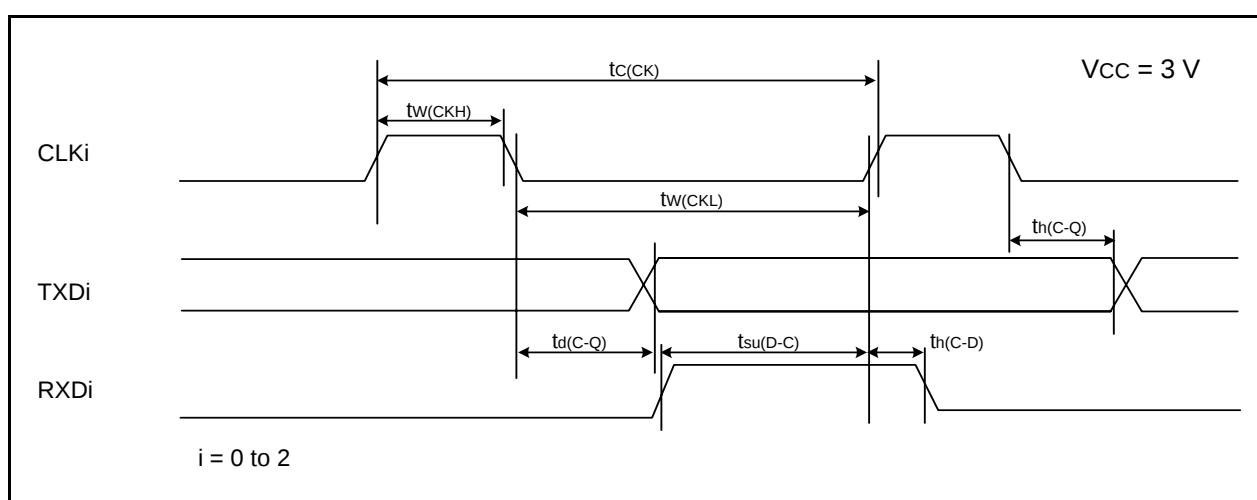
**Figure 5.15 TRFI Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.28 Serial Interface

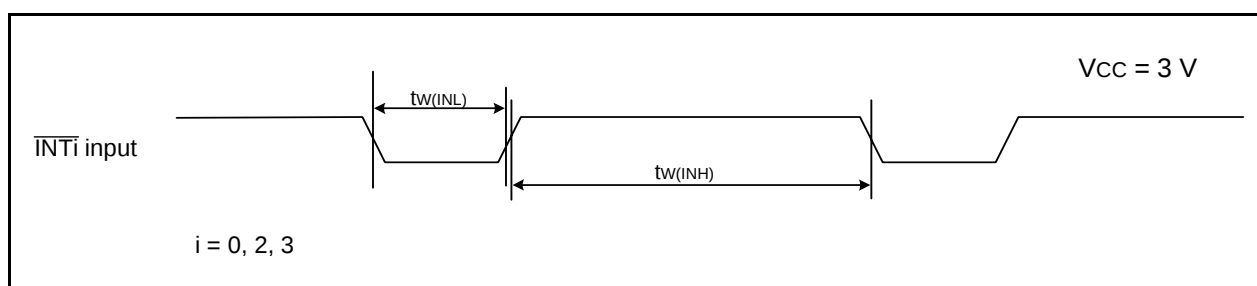
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi Input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

 $i = 0 \text{ to } 2$ **Figure 5.16 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.29 External Interrupt $\overline{INTi}$ ($i = 0, 2, 3$) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	380 ⁽²⁾	—	ns

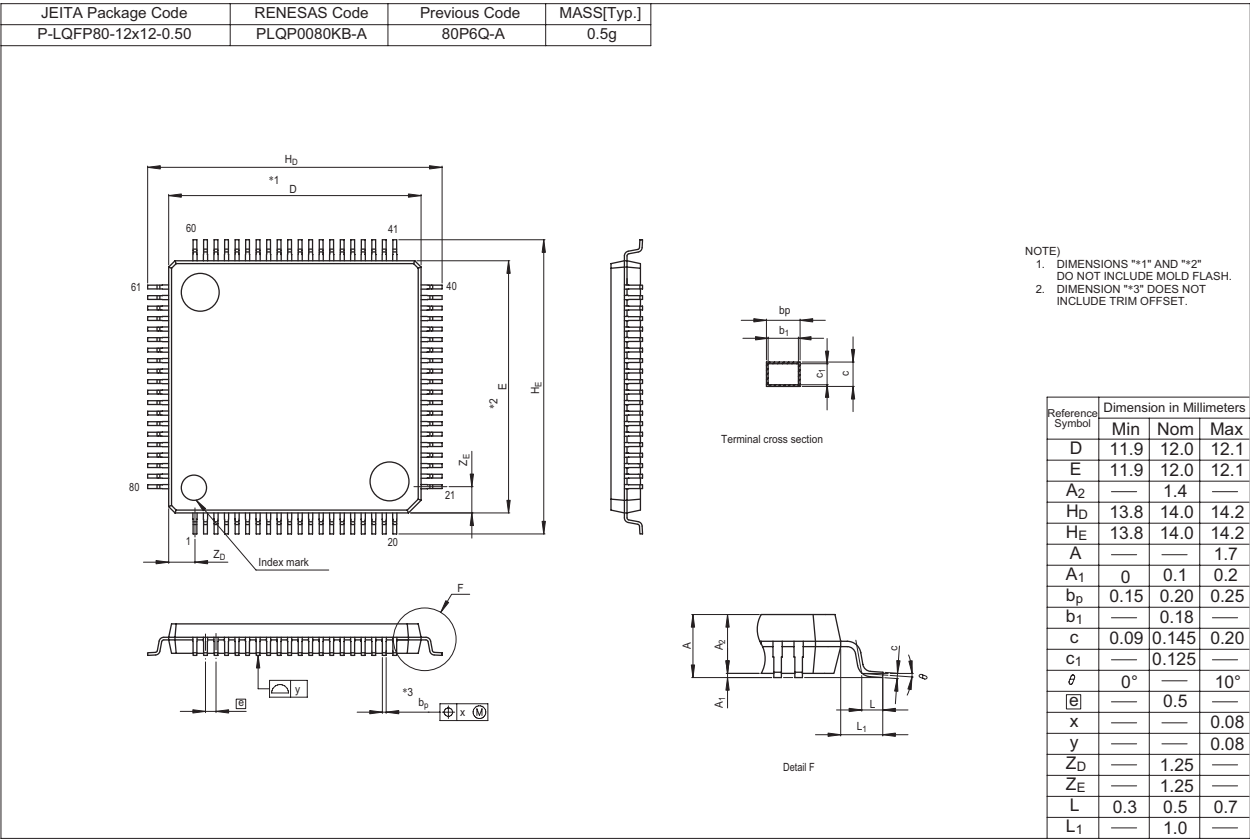
NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency $\times$ 3) or the minimum value of standard, whichever is greater.

**Figure 5.17 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 3 V**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.



REVISION HISTORY	R8C/2C Group, R8C/2D Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.01	Apr 03, 2006	–	First Edition issued
0.10	Jun 26, 2006	All pages	Pin name revised CMP0_0 → TRFO00, CMP0_1 → TRFO01, CMP0_2 → TRFO02, CMP1_0 → TRFO10, CMP1_1 → TRFO11, CMP1_2 → TRFO12, TRFIN → TRFI
		2, 4	Table 1.1 Specifications for R8C/2C Group (1) and Table 1.3 Specifications for R8C/2D Group (1); I/O Ports: • Input-only: 3 pins → 2 pins revised Interrupts: • Internal: 17 sources → 23 sources revised
		3, 5	Table 1.2 Specifications for R8C/2C Group (2) and Table 1.4 Specifications for R8C/2D Group (2); ROM Correction Function deleted
		8	Figure 1.3 Block Diagram revised
		9	Figure 1.4 Pin Assignment (Top View) revised
		10, 11	Table 1.7 Pin Name Information by Pin Number (1) and Table 1.8 Pin Name Information by Pin Number (2) revised
		12, 13	Table 1.9 Pin Functions (1) and Table 1.10 Pin Functions (2) revised
		19	Table 4.1 SFR Information (1); • 0008h: Module Standby Control Register, MSTCR, 00h added • 001Ch: “00h” → “00h, 10000000b” revised • NOTE6 added
		20	Table 4.2 SFR Information (2); • 005Fh: Capture Interrupt Control Register, CAPIC, XXXXX000b added
		22	Table 4.4 SFR Information (4); • 00DCh: “00DDh” → “00DCh” revised • 00F5h: “XXXX00XXb” → “00h” revised
		23	Table 4.5 SFR Information (5); • 0105h: LIN Special Function Register, LINCR2, 00h added
		31	Package Dimensions; “Diagrams showing the latest package dimensions ... in the “Packages” section of the Renesas Technology website.” added
0.20	Sep 15, 2006	31 to 54	5. Electrical Characteristics added
0.30	Dec 22, 2006	6	Table 1.5 and Figure 1.1 revised
		7	Table 1.6 and Figure 1.2 revised
		17	Figure 3.1 revised
		18	Figure 3.2 revised
		19	Table 4.1; • 000Ah: “00XXX000b” → “00h” revised • 0008h: “Module Standby Control Register” → “Module Operation Enable Register” revised • 000Fh: “00011111b” → “00X11111b” revised
		37	Table 5.11 revised